Tel: 603-883-1500
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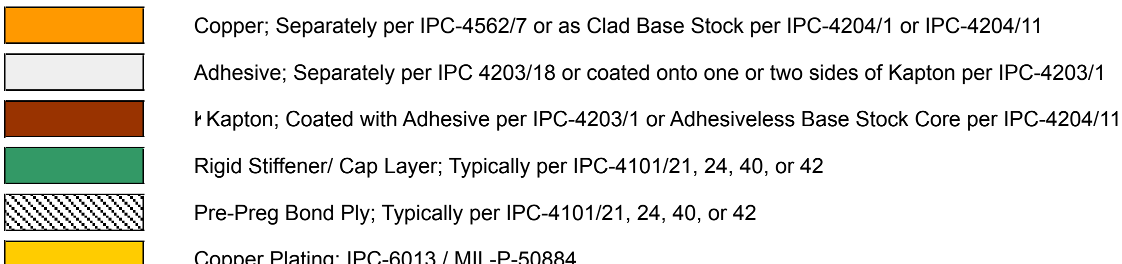
Typical Material Stack up
for Type 4 Multi-Layer Flex Circuits

With Segmented Covercoats

Layer	Description
Layer 1	GFN or GIN Rigid Cap Layer
Pouch Ly 1	Optional
Pre-Preg	
Pre-Preg	
Layers 2 & 3	Covercoated in unbonded area(s).
Pre-Preg	
Pre-Preg	
Pre-Preg	
Layers 4 & 5	Covercoated in unbonded area(s).
Pre-Preg	
Pre-Preg	
Pouch Ly 6	Optional
Layer 6	GFN or GIN Rigid Cap Layer

Material Legend



Note: Adhesive or Adhesiveless Base Stocks may be used. Individual material layer thicknesses may be adjusted as required.